SN54ABT16640, SN74ABT16640 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS107C – APRIL 1992 – REVISED JANUARY 1997

SN54ABT16640 . . . WD PACKAGE **Members of the Texas Instruments** SN74ABT16640 . . . DGG OR DL PACKAGE Widebus[™] Family (TOP VIEW) State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation 1DIR 48 0 1 OE Latch-Up Performance Exceeds 500 mA Per 47 1A1 1B1 2 **JEDEC Standard JESD-17** 1B2 3 46 1A2 Typical V_{OLP} (Output Ground Bounce) < 1 V • 45 GND GND 4 at V_{CC} = 5 V, T_A = 25°C 1B3 5 44 A 1A3 1B4 6 43 AA4 • Distributed V_{CC} and GND Pin Configuration 42 V_{CC} V_{CC} [] 7 Minimizes High-Speed Switching Noise 41 🛛 1A5 1B5 8 • Flow-Through Architecture Optimizes PCB 1B6 9 40 1A6 Layout GND [] 10 39 GND High-Drive Outputs (-32-mA I_{OH}, 38 1A7 1B7 11 $64 \text{-mA} I_{OI}$) 37 1A8 1B8 12 **Package Options Include Plastic 300-mil** 2B1 13 36 2A1 Shrink Small-Outline (DL) and Thin Shrink 2B2 11 14 35 2A2 Small-Outline (DGG) Packages, and 380-mil 34 GND GND [] 15 Fine-Pitch Ceramic Flat (WD) Package 33 2A3 2B3 16 Using 25-mil Center-to-Center Spacings 32 2A4 2B4 17 31 V_{CC} V_{CC} [18 description 30 2A5 2B5 19 2B6 20 29 2A6

The 'ABT16640 are inverting 16-bit transceivers designed for asynchronous communication between data buses.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (1DIR and 2DIR) inputs. The output-enable ($1\overline{OE}$ and $2\overline{OE}$) inputs can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

GND 21

2B7 🛛 22

2B8 23

2DIR 224

28 GND

27 2A7

26 2A8

25 20E

The SN54ABT16640 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16640 is characterized for operation from -40° C to 85° C.

	(each 8-bit section)										
	INP	UTS									
	OE	DIR	OPERATION								
ĺ	L	L	B data to A bus								
	L	Н	A data to B bus								

Х

Н

FUNCTION TABLE



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Isolation

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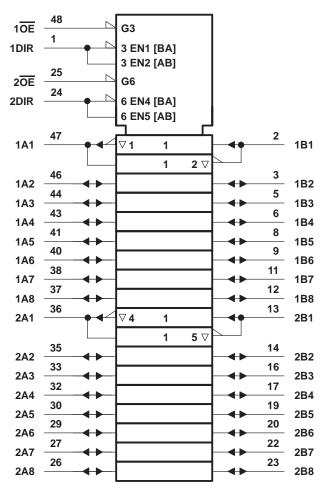
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

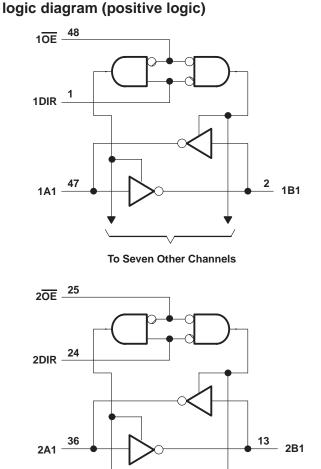


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logic symbol[†]





To Seven Other Channels

⁺ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1) Voltage range applied to any output in the high or power-off state, V _O Current into any output in the low state, I _O : SN54ABT16640	
SN74ABT16640	
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DGG package	
DL package	
Storage temperature range, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



SN54ABT16640, SN74ABT16640 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS107C – APRIL 1992 – REVISED JANUARY 1997

recommended operating conditions (see Note 3)

			SN54AB	Г16640	SN74AB1	Г16640	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	VCC	0	VCC	V
ЮН	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	AMETER	TEST CON	TEST CONDITIONS			;	SN54AB	Г16640	SN74ABT	UNIT		
PAR	AMEIER	TESTCO	IDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
VOH		$V_{CC} = 5 V,$	I _{OH} = -3 mA	3			3		3		V	
		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
		VCC = 4.3 V	I _{OL} = 64 mA			0.55*				0.55	v	
V _{hys}					100						mV	
lı	Control inputs	V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±1		±1		±1	μA	
	A or B ports					±100		±100		±100		
IOZH‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50		50		50	μΑ	
Iozl‡		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50		-50		-50	μA	
loff		V _{CC} = 0,	V_I or $V_O \leq 4.5~V$			±100				±100	μA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-40	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0,$	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
	Doto inputo	$V_{CC} = 5.5 V,$ One input at 3.4 V,	Outputs enabled			1		1.5		1		
∆ICC [¶]	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
Cio	A or B ports	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$			8						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

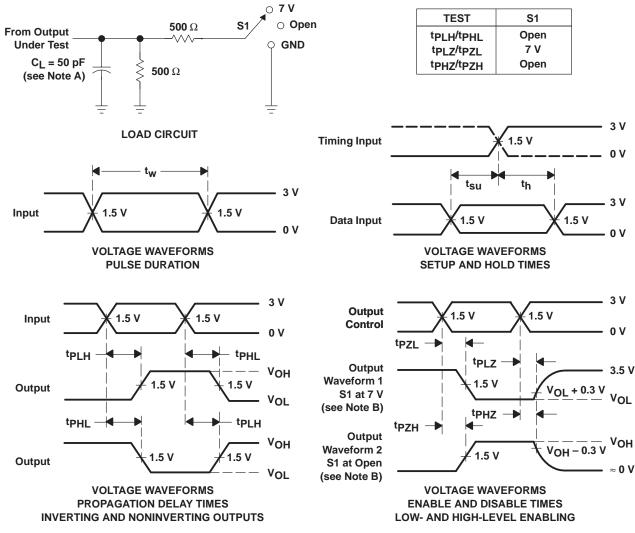
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(Tj	CC = 5 V A = 25°C	l, ;	MIN	мах	UNIT
			MIN	TYP	MAX			
^t PLH	A or P	A or B B or A	0.5	2.5	4.1	0.5	5.2	ns
^t PHL	AUD		0.5	2.8	4	0.5	4.5	115
^t PZH	OE	A or B		3.5	5.2	0.5	6.2	ns
tPZL	OE	AUB	0.5	3.9	6	0.5	7.4	115
^t PHZ	OE	A or B	0.5	3.8	6.8	0.5	7.9	ns
^t PLZ			0.5	3	4.5	0.5	5	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍ T	CC = 5 V A = 25°C	!, ;	MIN	МАХ	UNIT
			MIN	TYP	MAX			
^t PLH	A or B	A or B B or A		2.5	3.4	1	4.3 ns	
^t PHL	AUB	DOLY	1.1	2.8	3.6	1.1	3.9	115
^t PZH	OE	A or B	1.2	3.5	4.5	1.2	5.5	ns
^t PZL	UE	AUD	1.5	3.9	5	1.5	6.3	115
^t PHZ	OE	A or B	1.8	3.8	4.8	1.8	6.3	ns
^t PLZ	UE	AUD	1.5	3	3.9	1.5	4.2	115



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns. t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74ABT16640DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16640	Samples
SN74ABT16640DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16640	Samples
SN74ABT16640DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16640	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Dec-2020

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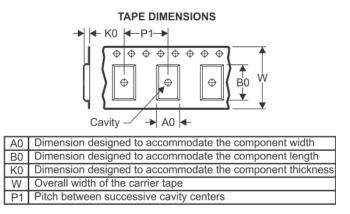
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



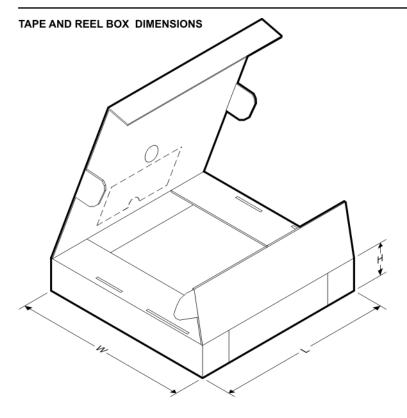
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16640DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT16640DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



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PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16640DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABT16640DLR	SSOP	DL	48	1000	367.0	367.0	55.0



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TUBE

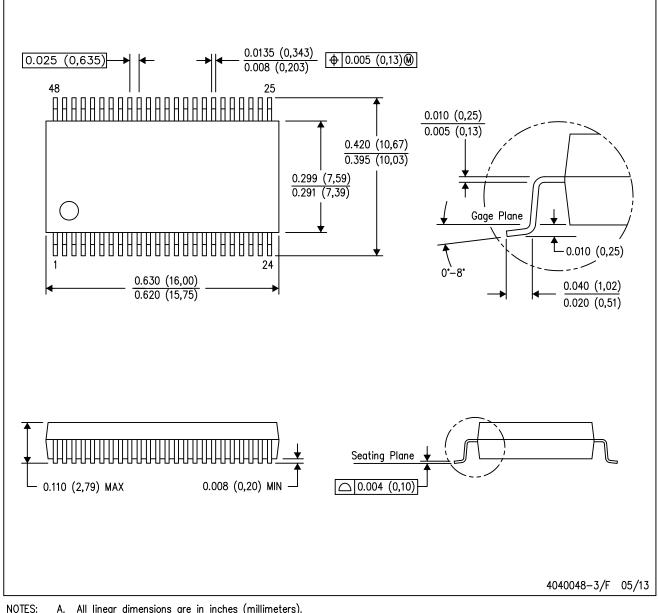


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ABT16640DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

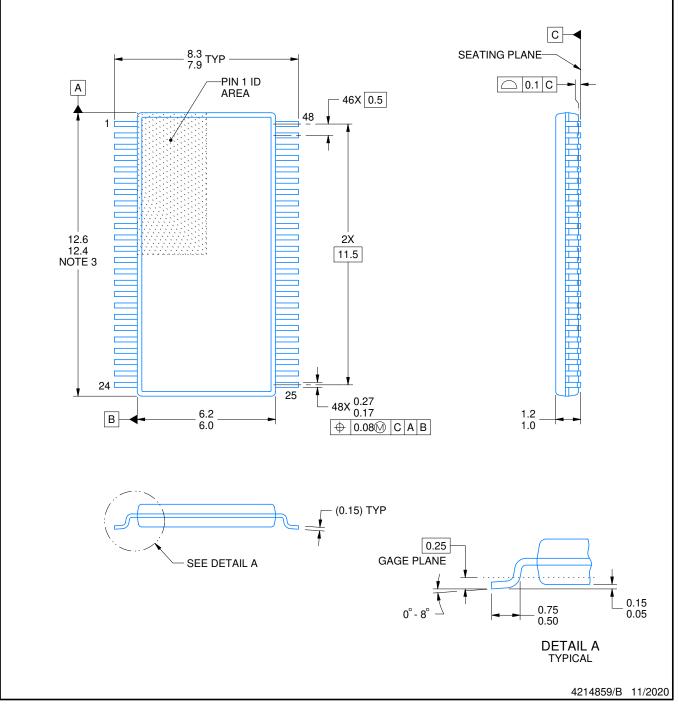
PowerPAD is a trademark of Texas Instruments.



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not

- exceed 0.15 mm per side. 4. Reference JEDEC registration MO-153.



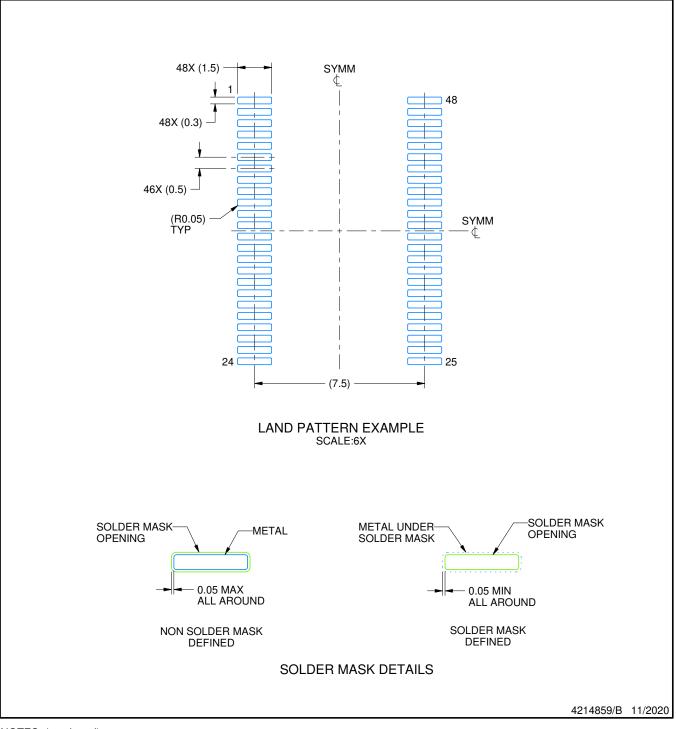
DGG0048A

DGG0048A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

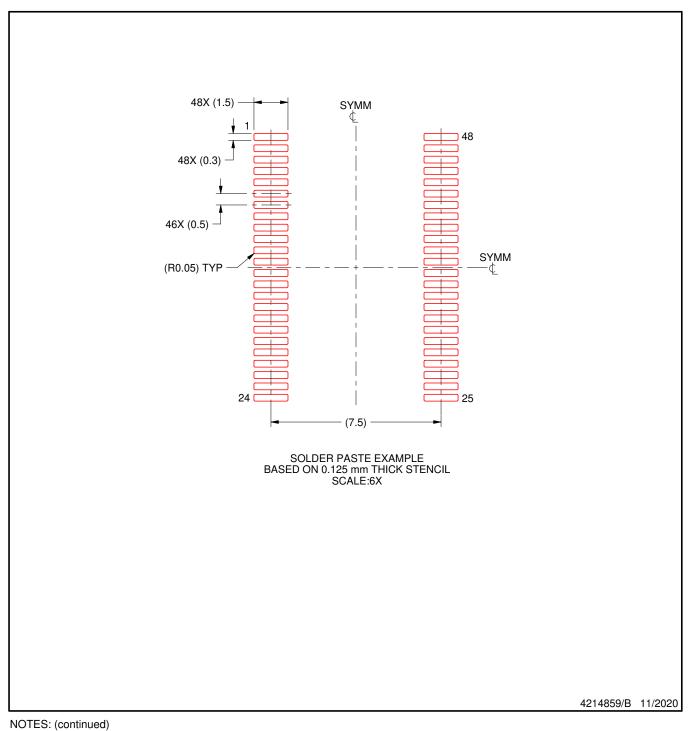


DGG0048A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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